

**Product / Package Information**

Package	LFCSP - Sawn
Body Size (mm)	7 X 7 X 0.75 (5.6 EP)
Lead Count	48
Terminal Finish	100 Sn

**Environmental Compliance Information**

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	3.51E-02	86.2	862000	24.96		249635
Thermosets	Epoxy resin	Proprietary	2.44E-03	6.0	60000	1.74		17376
Thermosets	Phenol resin	Proprietary	2.44E-03	6.0	60000	1.74		17376
Other inorganic materials	Metal Hydroxide	Proprietary	6.10E-04	1.5	15000	0.43		4344
Other inorganic materials	Carbon black	1333-86-4	1.22E-04	0.3	3000	0.09		869
Subtotal			4.07E-02	100.00	1000000	28.96		289599

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	8.31 E-02	97.50	975000	59.14		591441
Copper & its alloys	Iron	7439-89-6	2.00 E-03	2.35	23500	1.43		14255
Copper & its alloys	Zinc	7440-66-6	1.02 E-04	0.12	1200	0.07		728
Copper & its alloys	Phosphorus	7723-14-0	2.56 E-05	0.03	300	0.02		182
Subtotal			8.52 E-02	100.00	1000000	60.66		606606

**Internal Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	1.14 E-03	100.0	1000000	0.81		8116

**External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	4.80 E-04	100.0	1000000	0.34		3417

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	1.26 E-03	100.0	1000000	0.90		8970

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	1.02 E-02	100.0	1000000	7.23		72329

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	1.13 E-03	73.54	735400	0.81		8062
Other organic materials	Epoxy resin A	TS ref# 10013	1.13 E-04	7.35	73500	0.08		806
Others	Anhydride	TS ref# 10181	1.13 E-04	7.35	73500	0.08		806
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	4.53 E-05	2.94	29400	0.03		322
Other organic materials	Epoxy resin B	TS ref# 10237	4.53 E-05	2.94	29400	0.03		322
Others	Epoxy resin modifier	TS ref# 10038	4.53 E-05	2.94	29400	0.03		322
Others	Anhydride	TS ref# 10180	4.53 E-05	2.94	29400	0.03		322
Subtotal			1.54 E-03	100.00	1000000	1.10		10963

<b>Package Totals</b>	<b>Weight (g)</b>	<b>Percentage (%)</b>	<b>PPM</b>
	1.40 E-01	100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary

**Product / Package Information**

Package	LFCSP - Sawn
Body Size (mm)	7 X 7 X 0.75 (5.6EP)
Lead Count	48
Terminal Finish	NiPdAu

**Environmental Information**

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.39E-02	83.25	832500	24.19	241918
Thermosets	Epoxy resin	Proprietary	2.20E-03	5.42	54200	1.58	15750
Thermosets	Phenol resin	Proprietary	1.40E-03	3.45	34500	1.00	10025
Other inorganic materials	Metal Hydroxide	Proprietary	2.20E-03	5.42	54200	1.58	15750
Others	Others	Proprietary	1.00E-03	2.46	24600	0.71	7149
Subtotal			4.07E-02	100.00	1000000	29.06	290592

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	8.31 E-02	97.50	975000	59.35	593469
Copper & its alloys	Iron	7439-89-6	2.00 E-03	2.35	23500	1.43	14304
Copper & its alloys	Zinc	7440-66-6	1.02 E-04	0.12	1200	0.07	730
Copper & its alloys	Phosphorus	7723-14-0	2.56 E-05	0.03	300	0.02	183
Subtotal			8.52 E-02	100.00	1000000	60.87	608686

**Internal / External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	1.11 E-03	97.3	972697	0.79	7921
Precious metals	Palladium	7440-05-3	2.58 E-05	2.3	22621	0.02	184
Precious metals	Gold	7440-57-5	5.34 E-06	0.5	4683	0.00	38
Subtotal			1.14 E-03	100.00	1000000	0.81	8143

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.25 E-03	99	990000	0.89	8911
Precious metals	Palladium	7440-05-3	1.26 E-05	1.0	10000	0.01	90
Subtotal			1.26 E-03	100.0	1000000	0.90	9001

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.02 E-02	100.0	1000000	7.26	72577

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4					
Thermoset	Epoxy Resin	9003-36-5 / 30583-72-3					
Other organic materials	t-butyl phenyl glycidyl ether	3101-60-8					
Other organic materials	Phenolic hardener	92-88-6 / 26834-02-6					
Other organic materials	Butyl cellosolve acetate	112-07-2					
Subtotal			1.54 E-03	100.0	1000000	1.10	11001

<b>Package Totals</b>	<b>Weight (g)</b>	<b>1.40 E-01</b>	<b>Percentage (%)</b>	<b>100.00</b>	<b>PPM</b>	<b>1000000</b>
-----------------------	-------------------	------------------	-----------------------	---------------	------------	----------------

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary